



Emerging Interconnection Networks Across Scales

Guest Editor:

Dr. Amlan Ganguly

Department of Computer
Engineering, Rochester Institute of
Technology, Rochester, NY
14623, USA

Deadline for manuscript
submissions:

closed (15 December 2018)

Message from the Guest Editor

To advance and capture the recent and future innovations in interconnection technology at multiple scales, such as on-chip networks, chip-to-chip interconnections and data center networks, the proposed Special Issue of *JLPEA* will be dedicated towards innovative ways of interconnecting electronic devices. The readers of this Special Issue will be able to familiarize themselves with the recent advances in these technology paradigms, while also discovering the common and disparate issues about these interconnections at these various scales. Original contributions from the following non-exhaustive list of topics are solicited:

- Power efficiency in Network-on-Chip
- Chip-to-chip interconnections
- Interconnections for heterogeneous systems
- Dynamic interconnection networks
- Data center networks
- 3D NoC
- Photonic/optical interconnects
- RF interconnections
- Wireless interconnects
- Millimeter-wave wireless communication for computing platforms
- THz band communications for computing systems
- Security and Privacy in NoC
- Data center network security and privacy
- Congruence of interconnection networks with IoT





an Open Access Journal by MDPI

Editor-in-Chief

Dr. Davide Bertozzi

Reader in Advanced Processing
Technologies, Department of
Computer Science, University of
Manchester, Manchester M13
9PL, UK

Message from the Editor-in-Chief

Journal of Low Power Electronics and Applications is an open access journal which provides an advanced forum for rapid dissemination of innovative research and important results in all aspects of low power electronics and design.

It publishes reviews, regular research papers and short communications. Our aim is to encourage scientists to publish their experimental and theoretical results in as much detail as possible. The full experimental details must be provided so that the results can be reproduced.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, ESCI (Web of Science), Inspec, and other databases.

Rapid Publication: manuscripts are peer-reviewed and a first decision is provided to authors approximately 24.2 days after submission; acceptance to publication is undertaken in 3.8 days (median values for papers published in this journal in the second half of 2025).

Contact Us

Journal of Low Power Electronics and Applications Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/jlpea
jlpea@mdpi.com
X@JLPEA_MDPI